

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
		S51 and ((multi\$5 with layer) multi\$layer\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:48
		capacitor.ti. and ((third with substrate with electrode) same (multiple with (dielectrics layers)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:28
		capacitor.ti. and ((third with substrate with electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:27
		(solder adj wave	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/13 16:59
		S33 and (components near3 (rear back backside "both sides"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:19
L1	0	361/312,313.pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:14
L2	1022	361/312,313.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:18
L3	280	361/312.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:14

L4	794	361/313.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:15
L5	75	361/312,313.ccls. and isolation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:34
L6	543	(data adj access adj arrangement).ab. or (daa).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:22
L7	2533	379/391,399.01,412,402,405,414, 442,443.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:25
L8	1122	379/399.01,412.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:36
L9	17	7 and ((multiple with layer) multi\$layer\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31
L10	1	7 and (substrate near4 dielectric) and capacitor and (pcb (printed adj circuit adj board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31
L11	3	7 and substrate near4 dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31
L12	446	7 and (data adj access adj arrang\$6).ab. or daa.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:32

L13	19	beutler.in. and rahamim.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:35
L14	172	379/399.01,412.ccls.	US-PGPUB	OR	ON	2005/07/21 09:36
S1	2372	379/391,399.01,412,402,405,414, 442,443.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/03 13:25
S2	5	((("4870746").PN.) ("5972053"). PN.) ("5978231").PN.) (("6021050").PN.) ("6043987"). PN.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/02 14:37
S3	4	"5972053".URPN.	USPAT	OR	OFF	2004/01/02 14:28
S4	26	("3913219" "3947956" "4416914" "4555745" "4566186" "4632845" "4774634" "4808434" "4870746" "5225969" "5298687" "5305523" "5347258" "5354599" "5384434" "5428190" "5502889" "5527998" "5599595" "5688584" "5716663" "5727310" "5747222" "5758575" "5763058" "5814366").PN.	USPAT	OR	OFF	2004/01/02 14:29
S5	718	((pcb (printed adj circuit adj board)) and capacitor).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/02 14:38
S6	20	((((pcb (printed adj circuit adj board)) and capacitor).ti.) and copper and substrat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/02 15:04
S7	61992	substrate near4 dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31
S8	1483	(substrate near4 dielectric) and capacitor and (pcb (printed adj circuit adj board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31

S9	59	(substrate near4 dielectric) and (capacitor and (pcb (printed adj circuit adj board))).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 16:59
S10	4	("5920454" "6021563" "6025057" "6115233" "2002/0043399").PN.	USPAT	OR	OFF	2004/01/02 15:09
S11	2	"suspended interdigital capacitor"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/01/02 15:42
S12	1	("4322698").PN.	USPAT; USOCR	OR	OFF	2004/01/02 15:46
S13	1	("5870046").PN.	USPAT; USOCR	OR	OFF	2004/01/05 10:02
S14	32	("4053720" "4192978" "4292595" "4417099" "4529845" "4540854" "4567331" "4644526" "4741031" "4757528" "4835486" "4843339" "4864605" "4901275" "4993063" "4995111" "5097503" "5136630" "5204896" "5235634" "5245654" "5287107" "5329281" "5329585" "5369666" "5410594" "5428682" "5500894" "5500895" "5602912" "5655010" "5692041").PN.	USPAT	OR	OFF	2004/01/05 11:14
S15	1	("4961220").PN.	USPAT; USOCR	OR	OFF	2004/01/05 15:24
S16	19	("Re35064" "3644853" "4890192" "4994936" "5019468" "5027253" "5086370" "5114780" "5161086" "5161304" "5162977" "5172304" "5180645" "5289034" "5469324" "5473191" "5583739" "5828106" "5831810").PN.	USPAT	OR	OFF	2004/06/02 16:54
S17	465	(data adj access adj arrang\$6).ab. or daa.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:32

S18	0	((data adj access adj arrang\$6). ab. or daa.ab.) and (capacitor near4 embed\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:00
S19	0	((capacitor near4 embed\$4) same (pcb "circuit board" substrate)) and ((data adj access adj arrang\$6) or daa)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:01
S20	17	((capacitor near4 embed\$4) same (pcb "circuit board" substrate)) and modem	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:06
S21	20	("4002542" "4237522" "4295183" "4467450" "4673904" "4675717" "4714952" "4811082" "4827323" "4853491" "4889962" "5079069" "5134539" "5141603" "5177594" "5376818" "5414285" "5714241" "5780143" "5898574").PN.	USPAT	OR	OFF	2004/06/02 17:05
S22	2	"5765279".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:06
S23	6	("4590537" "5345361" "5347423" "5817543" "5895966" "6191932").PN.	USPAT	OR	OFF	2004/06/02 17:11
S24	33	("3034930" "3142047" "3348990" "3436819" "3469019" "3506482" "3742597" "3932932" "4187339" "4211603" "4301192" "4372046" "4388136" "4389278" "4417393" "4486738" "4522888" "4543715" "4554229" "4554732" "4584627" "4586972" "4590537" "4605915" "4616292" "4633035" "4635358" "4636018" "4642569" "4675717" "4739257" "4775573" "4908258").PN.	USPAT	OR	OFF	2004/06/02 17:20

S25	612	(capacitor near4 embed\$4) same (pcb "circuit board" substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:30
S26	2	"5796587".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/02 17:30
S27	13	("4775573" "4792779" "5010641" "5027253" "5079069" "5144526" "5155655" "5161086" "5162977" "5172304" "5261153" "5428499" "5469324").PN.	USPAT	OR	OFF	2004/06/02 17:32
S28	1968	(via and pcb).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:13
S29	1	S28 and ((back backside) same (cost cheap\$3 inexpensive) same components)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:15
S30	15918	((back backside) same (cost cheap\$3 inexpensive) same components)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:15
S31	740	((back backside) same (cost cheap\$3 inexpensive) same components same mount)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:15
S32	22	S31 and via and (pcb "printed circuit board" "circuit board")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:18

S33	248247	manufacturing near2 costs	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:18
S34	1677	S33 and (components near3 (rear back backside "both sides"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:19
S35	2473	379/391,399.01,412,402,405,414, 442,443.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 16:26
S36	0	("6137671").URPN.	USPAT	OR	OFF	2005/01/13 16:26
S37	19	("3644853" "4890192" "4994936" "5019468" "5027253" "5086370" "5114780" "5161086" "5161304" "5162977" "5172304" "5180645" "5289034" "5469324" "5473191" "5583739" "5828106" "5831810" "Re35064").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/13 16:58
S38	813	(solder adj wave)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/13 16:59
S39	26	S38 and pcb and front and (back rear)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/13 17:00
S40	12	S39 and cost	US-PGPUB; USPAT; USOCR	OR	OFF	2005/01/13 17:00
S41	2473	379/391,399.01,412,402,405,414, 442,443.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 18:25
S42	38	S41 and (capacitor same (embed\$4 pcb substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 18:25
S43	0	("6278356").URPN.	USPAT	OR	OFF	2005/07/20 11:17
S44	0	("6137671").URPN.	USPAT	OR	OFF	2005/07/20 11:23

S45	1798	capacitor.ti. and (third with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:24
S46	763	capacitor.ti. and (third with substrate with electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:24
S47	0	capacitor.ti. and ((third with substrate with electrode) same (sav\$4 with space))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:25
S48	3	capacitor.ti. and ((third with substrate with electrode) same (reduc\$4 with size))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:27
S49	763	capacitor.ti. and (third with substrate with electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:28
S50	10	capacitor.ti. and ((third with substrate with electrode) same (multiple with (dielectrics layers)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:47
S51	245	216/6.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 11:47
S52	58	S51 and ((multiple with layer) multi\$layer\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:31

S53	8	S51 and (((multiple with layer) multi\$layer\$3) same via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 09:14
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